

1           1.    An integrated circuit socket comprising:  
2                a socket housing;  
3                a hinged cover secured to said housing; and  
4                an infrared transmissive cap removably secured to  
5   said cover.

1           2.    The socket of claim 1 wherein said cap includes a  
2   plurality of openings formed through the cover to allow the  
3   passage of heated air.

1           3.    The socket of claim 1 including spring catches on  
2   opposed ends of said cap to removeably secure said cap to  
3   said cover.

1           4.    The socket of claim 1 wherein said cap transmits  
2   at least 80 percent of incident infrared radiation.

1           5.    The socket of claim 4 wherein said cap transmits  
2   at least 95 percent of incident infrared radiation.

1           6.    The socket of claim 1 wherein said cap is formed  
2   of plastic.

1           7.    The socket of claim 6 wherein said cap is formed  
2   of translucent red plastic.

1        8.    The socket of claim 1 wherein said cap includes  
2        standoffs to space said cap from said cover.

1        9.    The socket of claim 1 wherein said cap has a  
2        curved lower surface.

1        10.   The socket of claim 1 wherein said cap includes  
2        at least two apertures and downwardly extending prongs  
3        extending away from said apertures to reflect incident  
4        radiation passing through said apertures.

1        11.   A cap for an integrated circuit socket  
2        comprising:  
3                a body having apertures therethrough, said body  
4        formed of a material that is infrared transmissive; and  
5                tabs coupled to said body to removeably secure  
6        said body to an integrated circuit socket.

1        12.   The cap of claim 11 wherein said tabs include  
2        spring catches on opposed ends of said cap to removeably  
3        secure said cap to said socket.

1        13.   The cap of claim 1 wherein said cap transmits at  
2        least 80 percent of incident infrared radiation.

1        14. The cap of claim 13 wherein said cap transmits at  
2        least 95 percent of incident infrared radiation.

1        15. The cap of claim 11 wherein said cap is formed of  
2        plastic.

1        16. The cap of claim 15 wherein said cap is formed of  
2        translucent red plastic.

1        17. The cap of claim 11 wherein said cap includes  
2        standoffs to space said cap from said socket.

1        18. The cap of claim 11 wherein said cap has a curved  
2        side.

1        19. The cap of claim 11 wherein said apertures  
2        include downwardly extending prongs to reflect infrared  
3        radiation passing through said apertures.

1        20. The cap of claim 11 wherein said cap includes  
2        guides to guide said cap into alignment with said socket.

1        21. A method comprising:  
2                securing an infrared transmissive cap to an  
3        integrated circuit socket;

4                exposing said cap and said socket to infrared  
5 energy; and  
6                surface mounting said socket to a printed circuit  
7 board.

1            22. The method of claim 21 including exposing said  
2 cap and said socket to a surface mount reflow oven  
3 producing both infrared and convective heating.

1            23. The method of claim 21 including allowing heated  
2 air to circulate through said cap via apertures through  
3 said cap.

1            24. The method of claim 21 including providing an  
2 apertured, red plastic, infrared transmissive cap on said  
3 socket.

1            25. The method of claim 21 including enabling at  
2 least 80 percent of the infrared incident energy to pass  
3 through said cap to said socket.